Global Semiconductor Packaging Dicing Blades Market 2025 by Manufacturers, Regions, Type and Application, Forecast to 2031

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Abstracts

According to our (Global Info Research) latest study, the global Semiconductor Packaging Dicing Blades market size was valued at US$ 61.4 million in 2024 and is forecast to a readjusted size of USD 104 million by 2031 with a CAGR of 6.9% during review period.

Semiconductor packaging dicing blades are precision cutting tools used to dice or separate semiconductor wafers into individual chips or dies during the packaging process. These blades are typically ultra-thin and made from materials like resin-bonded diamond or metal-bonded diamond to ensure high precision, minimal chipping, and reduced kerf loss (material waste). They are essential in the semiconductor manufacturing process, especially for applications involving delicate or high-value wafers such as silicon, gallium arsenide, or sapphire. The choice of blade depends on factors like wafer material, thickness, and desired cut quality, and they play a critical role in ensuring the performance and yield of semiconductor devices.

This report is a detailed and comprehensive analysis for global Semiconductor Packaging Dicing Blades market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

In this report, we will assess the current U.S. tariff framework alongside international policy adaptations, analyzing their effects on competitive market structures, regional

economic dynamics, and supply chain resilience.

Key Features:

Global Semiconductor Packaging Dicing Blades market size and forecasts, in consumption value ($ Million), sales quantity (K Units), and average selling prices (US$/Unit), 2020-2031

Global Semiconductor Packaging Dicing Blades market size and forecasts by region and country, in consumption value ($ Million), sales quantity (K Units), and average selling prices (US$/Unit), 2020-2031

Global Semiconductor Packaging Dicing Blades market size and forecasts, by Type and by Application, in consumption value ($ Million), sales quantity (K Units), and average selling prices (US$/Unit), 2020-2031

Global Semiconductor Packaging Dicing Blades market shares of main players, shipments in revenue ($ Million), sales quantity (K Units), and ASP (US$/Unit), 2020-2025

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries
To assess the growth potential for Semiconductor Packaging Dicing Blades
To forecast future growth in each product and end-use market
To assess competitive factors affecting the marketplace

This report profiles key players in the global Semiconductor Packaging Dicing Blades market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Kinik Company, Toyo Adtec, Diamond Group, DISCO Corporation, ACCRETECH, Asahi Diamond Industrial, Norton Abrasive (Saint-Gobain), EHWA DIAMOND, A.L.M.T. Corp., NanJing Sanchao Advanced Materials, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

Semiconductor Packaging Dicing Blades market is split by Type and by Application. For the period 2020-2031, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

- Soft Blades
- Hard Blades

Market segment by Application

- 150mm Wafer
- 200mm Wafer
- 300mm Wafer
- Others

Major players covered

- Kinik Company
- Toyo Adtec
- Diamond Group
- DISCO Corporation
- ACCRETECH
- Asahi Diamond Industrial

Norton Abrasive (Saint-Gobain)

EHWA DIAMOND

A.L.M.T. Corp.

NanJing Sanchao Advanced Materials

Suzhou Sail Science & Technology

Zhengzhou Research Institute For Abrasives & Grinding (Sinomach)

System Technology

Market segment by region, regional analysis covers

North America (United States, Canada, and Mexico)
Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)
Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)
South America (Brazil, Argentina, Colombia, and Rest of South America)
Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe Semiconductor Packaging Dicing Blades product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of Semiconductor Packaging Dicing Blades, with price, sales quantity, revenue, and global market share of Semiconductor Packaging Dicing Blades from 2020 to 2025.

Chapter 3, the Semiconductor Packaging Dicing Blades competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the Semiconductor Packaging Dicing Blades breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2020 to 2031.

Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2020 to 2031.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2020 to 2025.and Semiconductor Packaging Dicing Blades market forecast, by regions, by Type, and by Application, with sales and revenue, from 2026 to 2031.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of Semiconductor Packaging Dicing Blades.

Chapter 14 and 15, to describe Semiconductor Packaging Dicing Blades sales channel, distributors, customers, research findings and conclusion.

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